

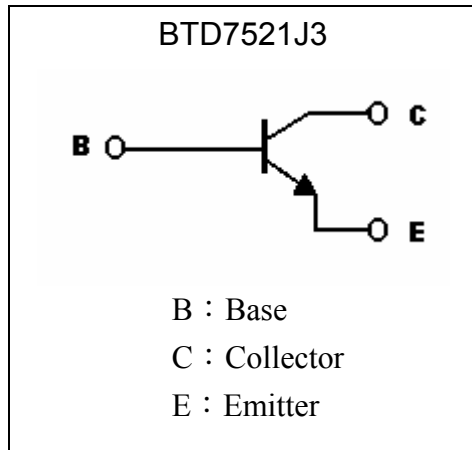
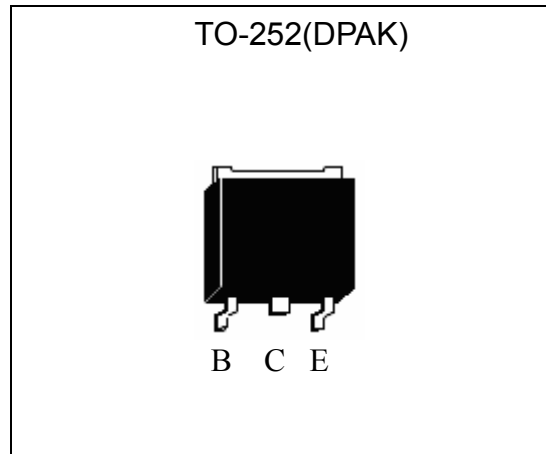
High Voltage NPN Epitaxial Planar Transistor

BTD7521J3

BV_{DSS}	90V
I_D	10A
$R_{CE(SAT)}$	0.1 Ω

Features

- High BV_{CEO}
- Very high current gain
- Pb-free lead plating package

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	90	V
Collector-Emitter Voltage	V_{CEO}	90	V
Emitter-Base Voltage	V_{EBO}	7	V
Collector Current (DC)	I_C	10	A
Collector Current (Pulse)	I_{CP}	20 (Note 1)	
Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	1.75 (Note 2)	W
Power Dissipation @ $T_c=25^\circ\text{C}$	P_D	30	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	71.4 (Note 2)	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	4.2	$^\circ\text{C/W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55~+150	$^\circ\text{C}$

- Note : 1. Single Pulse , $P_w \leq 300\mu\text{s}$, $Duty \leq 2\%$.
 2. When mounted on a PCB with the minimum pad size.

**Characteristics** (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	90	-	-	V	I _C =1mA, I _E =0
BV _{CEO}	90	-	-	V	I _C =10mA, I _B =0
BV _{EBO}	7	-	-	V	I _C =100μA, I _C =0
I _{CB0}	-	-	10	μA	V _{CB} =90V, I _E =0
I _{EBO}	-	-	10	μA	V _{EB} =7V, I _C =0
*V _{CE(sat)}	-	-	0.5	V	I _C =5A, I _B =50mA
*R _{CE(sat)}	-	-	0.1	Ω	I _C =5A, I _B =50mA
*V _{BE(sat)}	-	-	1.2	V	I _C =5A, I _B =50mA
*h _{FE}	1000	-	-	-	V _{CE} =5V, I _C =1A
*h _{FE}	500	-	-	-	V _{CE} =5V, I _C =5A
Cob	-	130	-	pF	V _{CB} =10V, f=1MHz

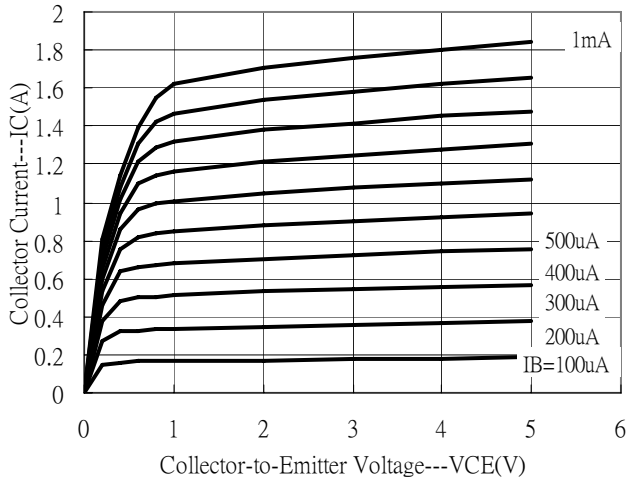
*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

Ordering Information

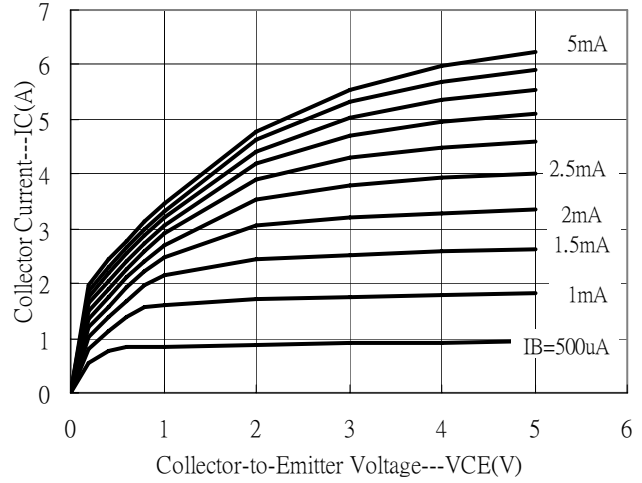
Device	Package	Shipping
BTD7521J3-0-T3-G	TO-252 (Pb-free lead plating and halogen-free package)	2500 pcs / Tape & Reel

Typical Characteristics

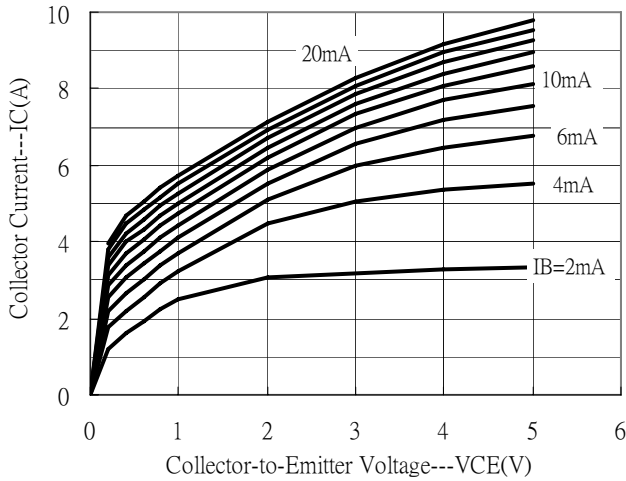
Emitter Grounded Output Characteristics



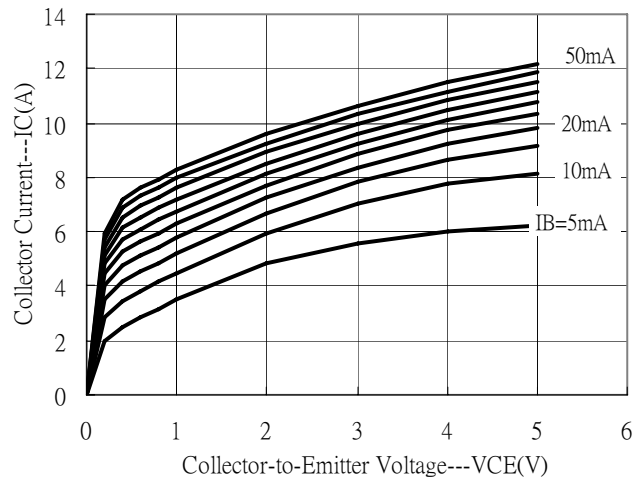
Emitter Grounded Output Characteristics



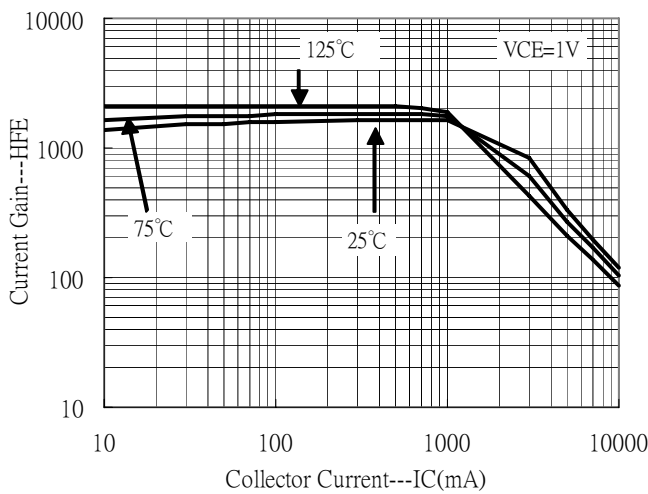
Emitter Grounded Output Characteristics



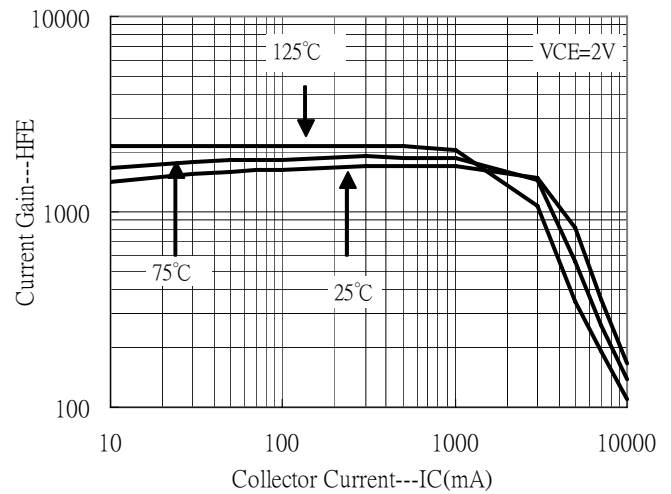
Emitter Grounded Output Characteristics

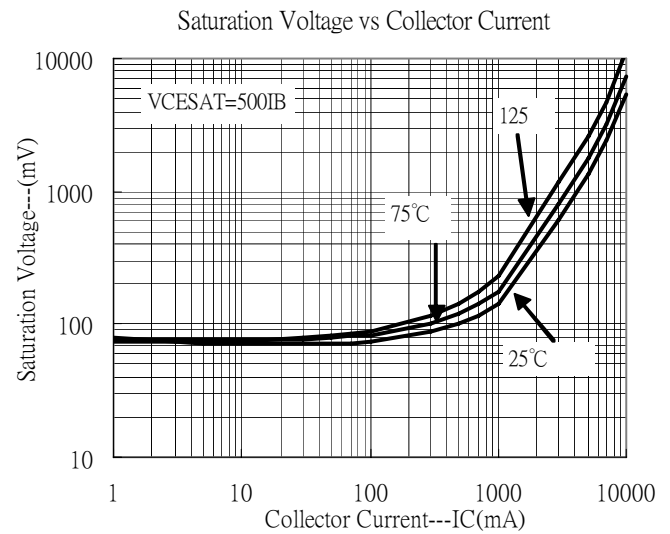
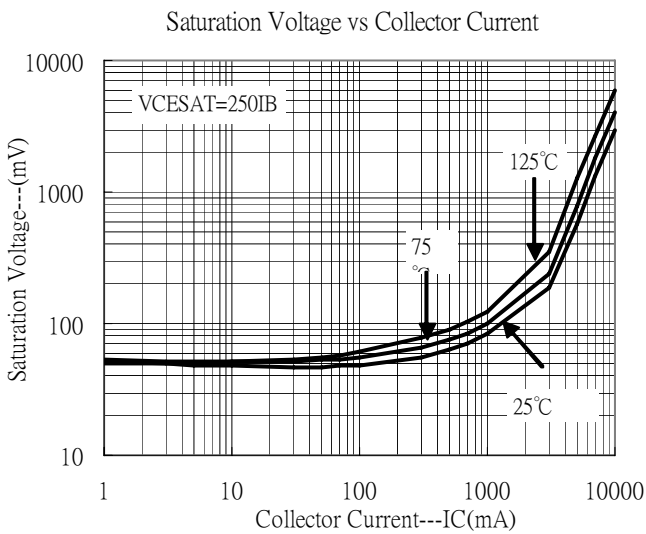
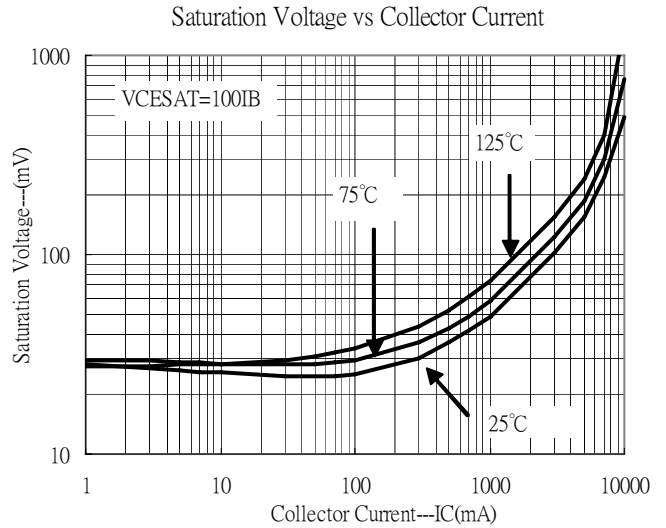
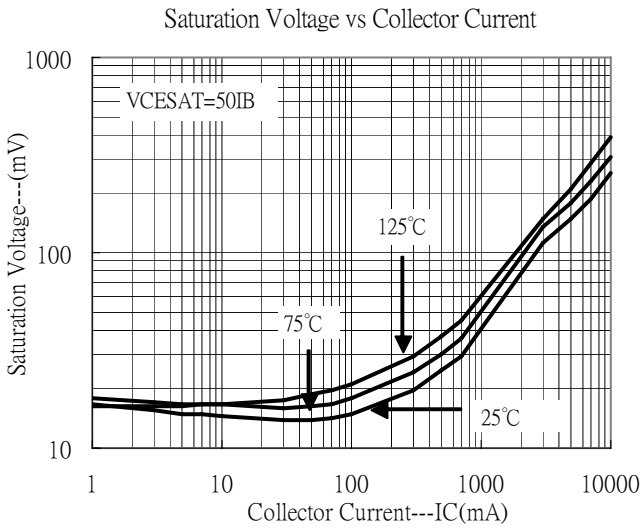
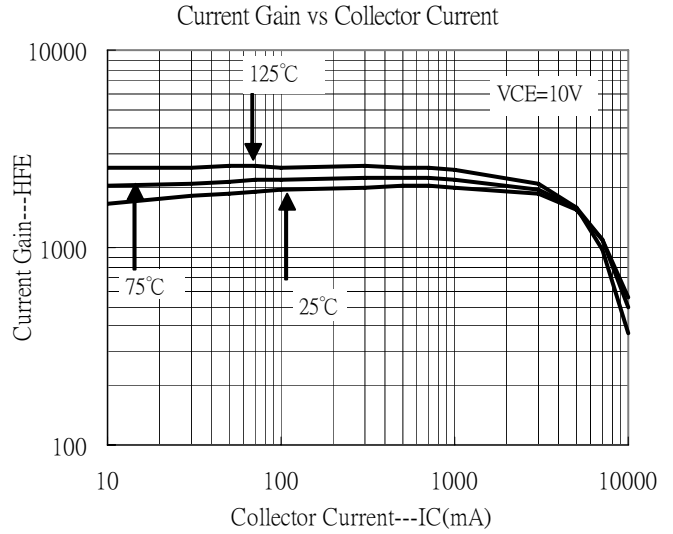
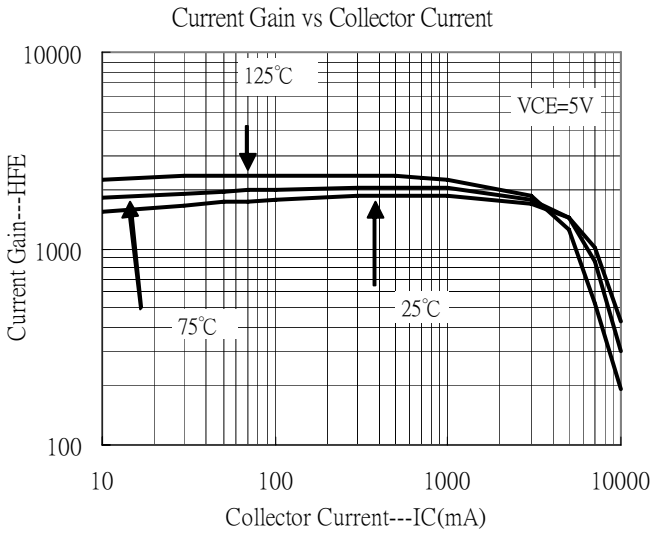


Current Gain vs Collector Current

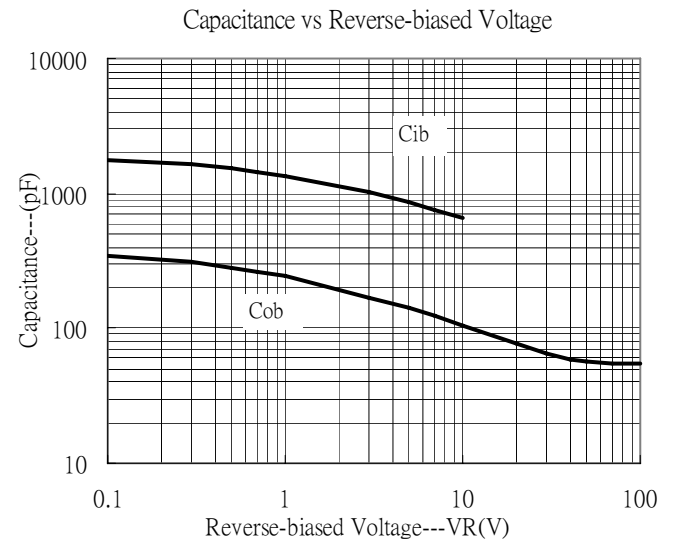
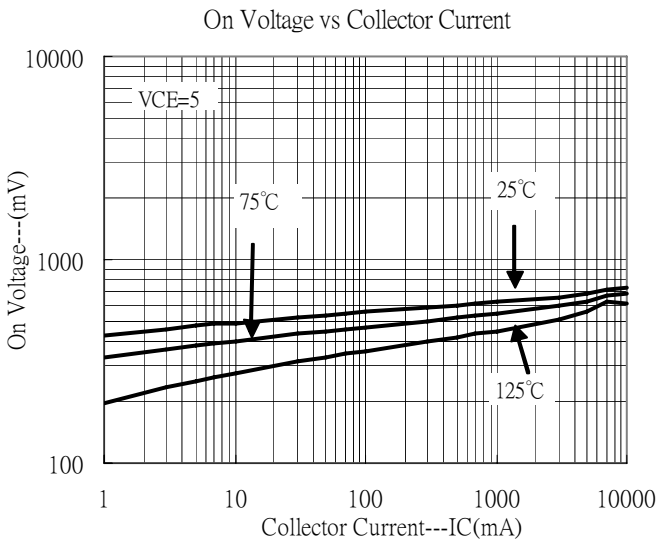
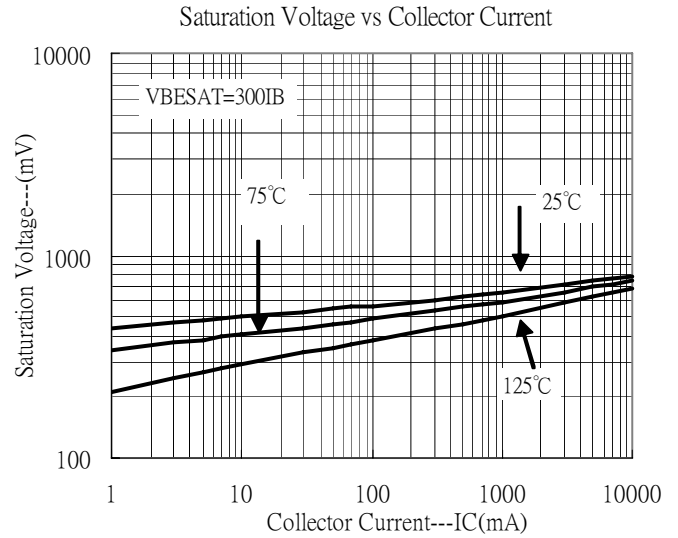
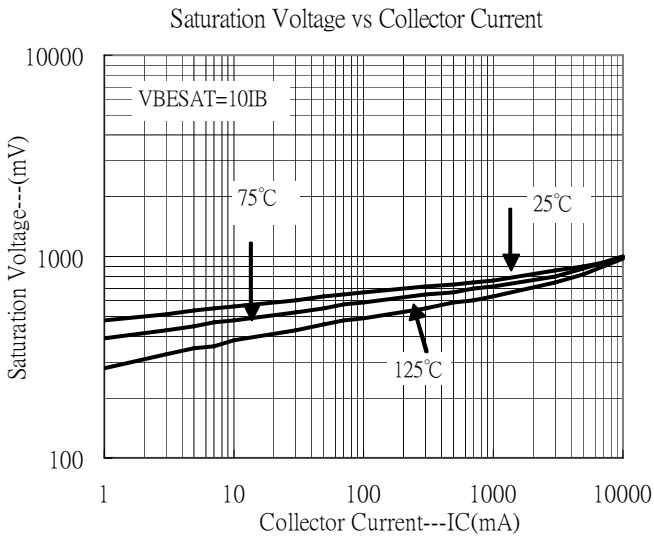
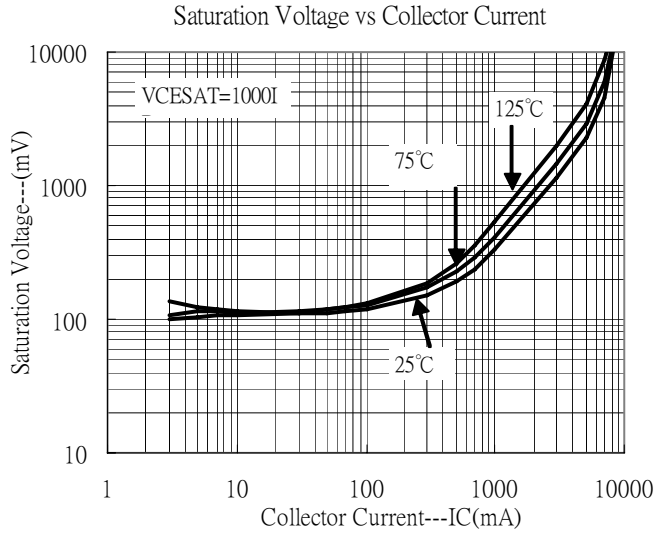
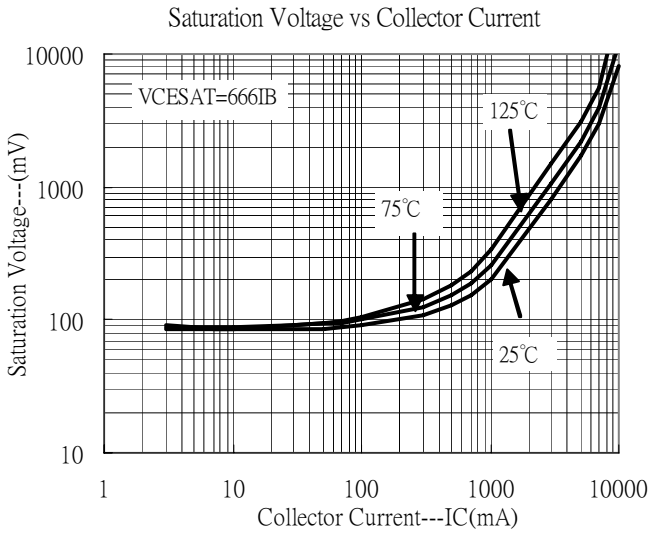


Current Gain vs Collector Current





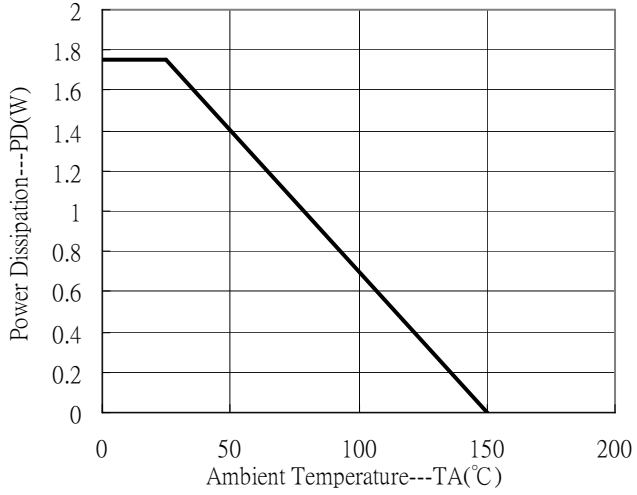
Typical Characteristics(Cont.)



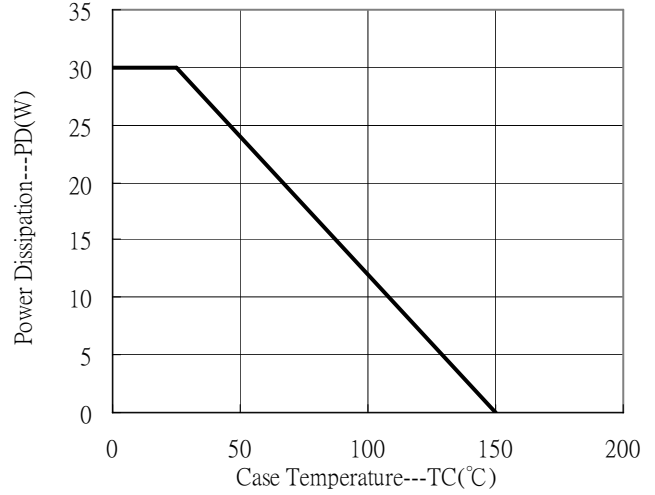


Typical Characteristics(Cont.)

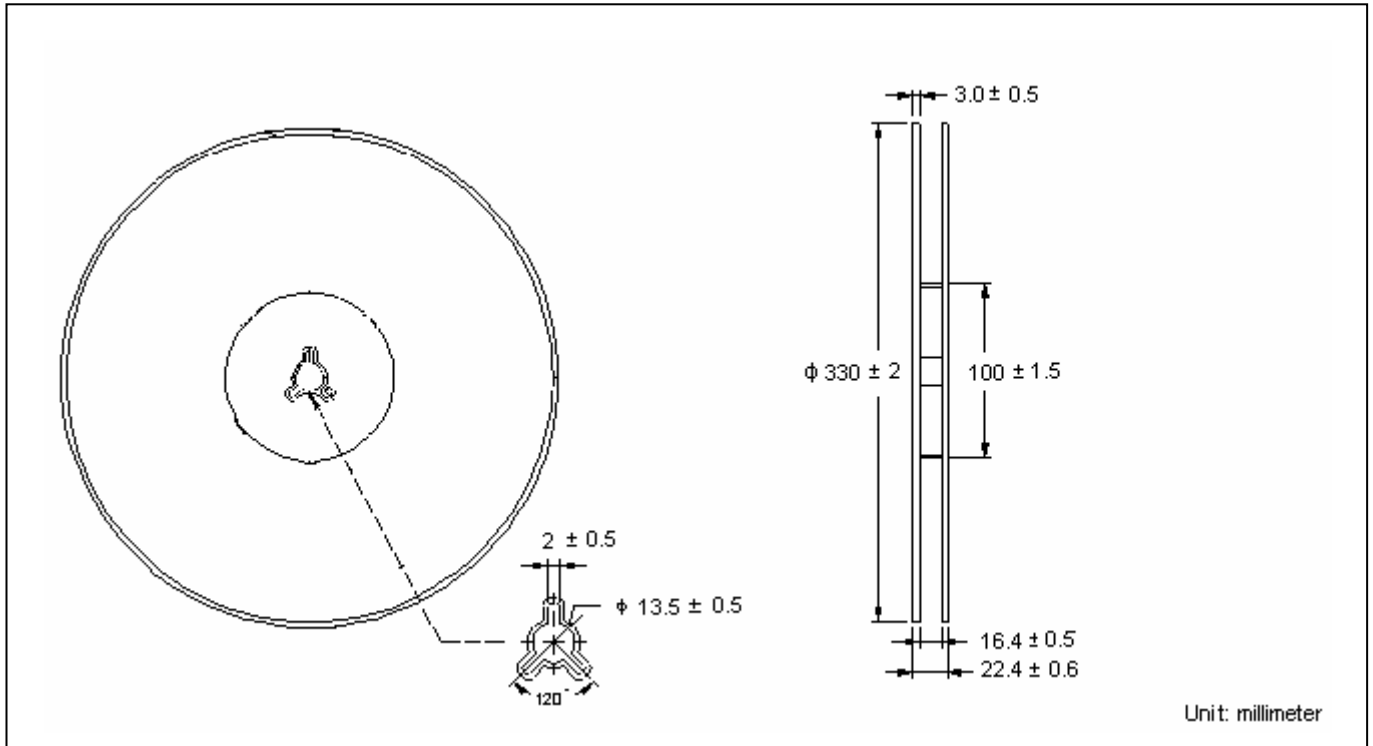
Power Derating Curve



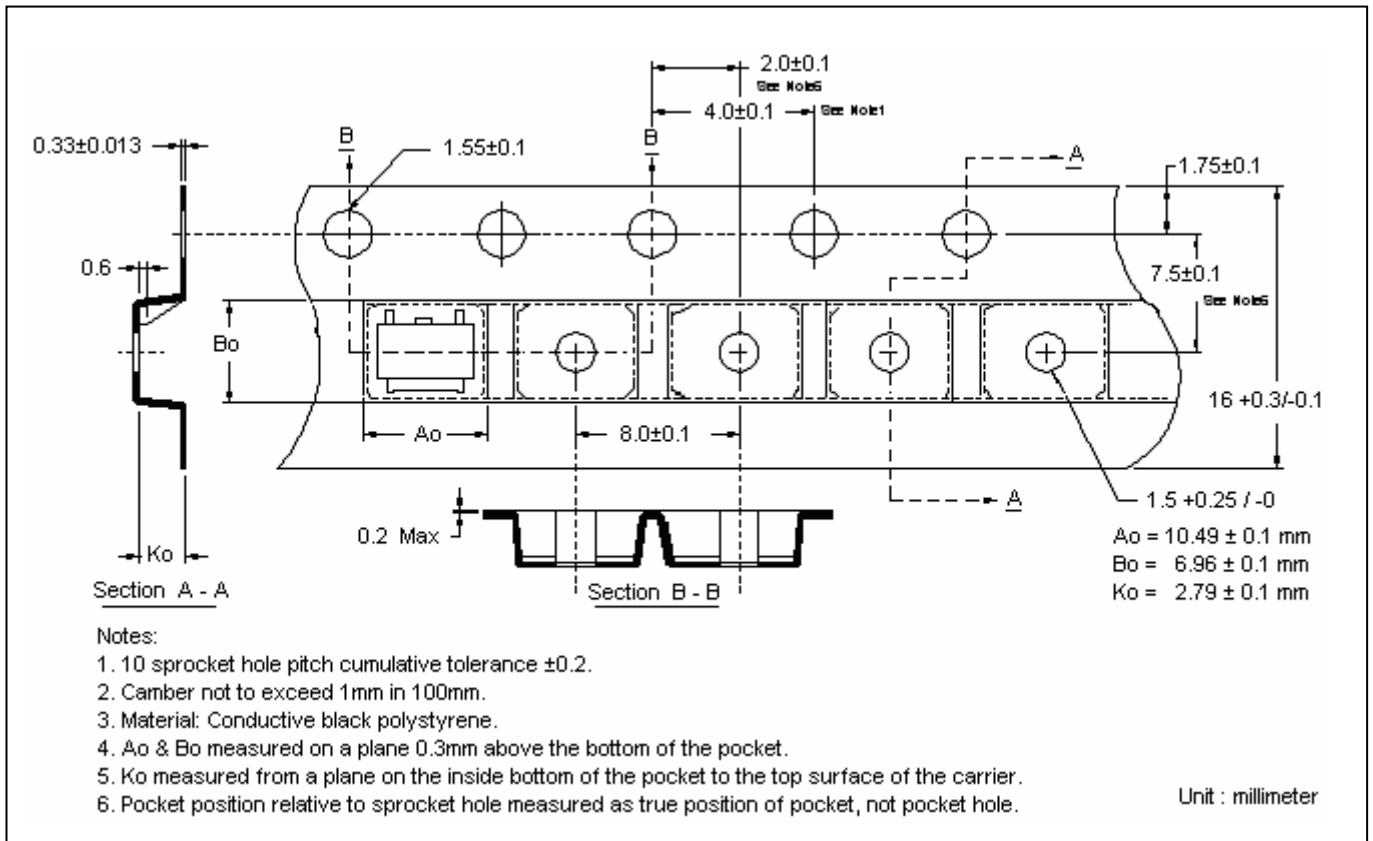
Power Derating Curve



Reel Dimension

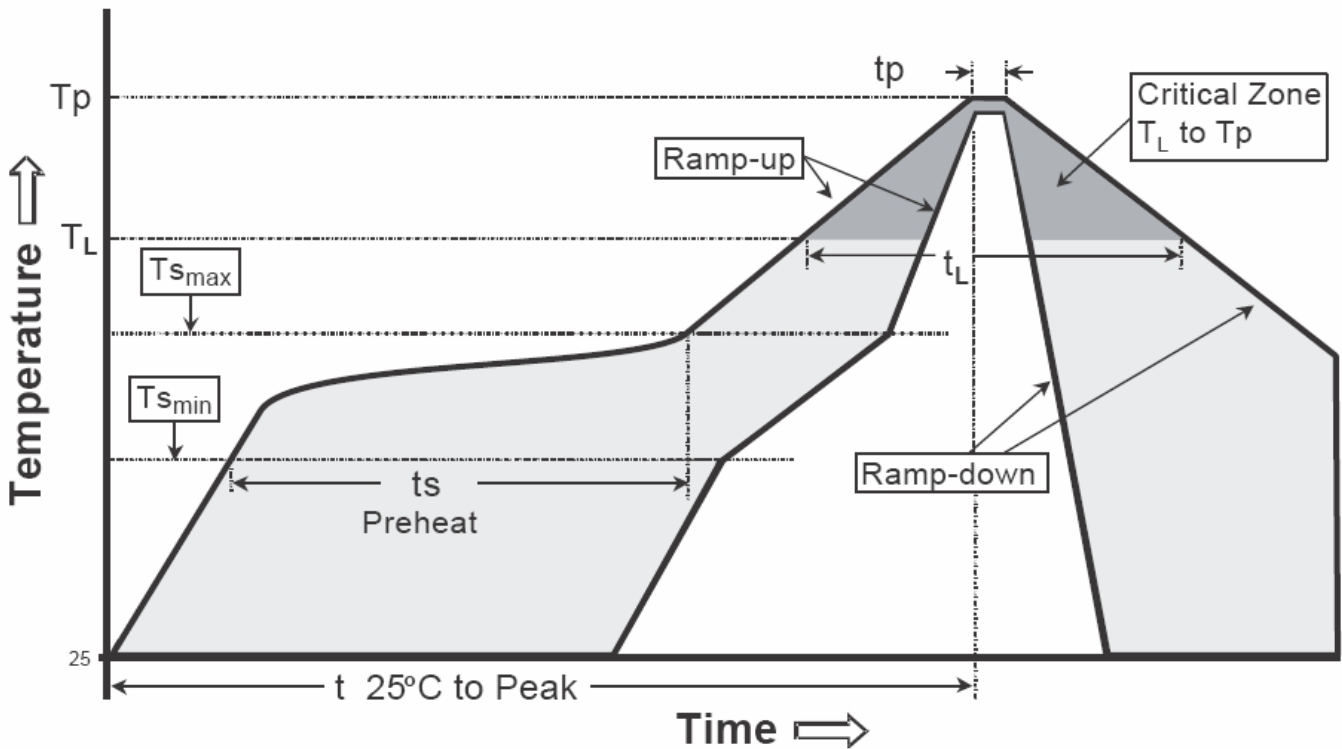


Carrier Tape Dimension



Recommended wave soldering condition

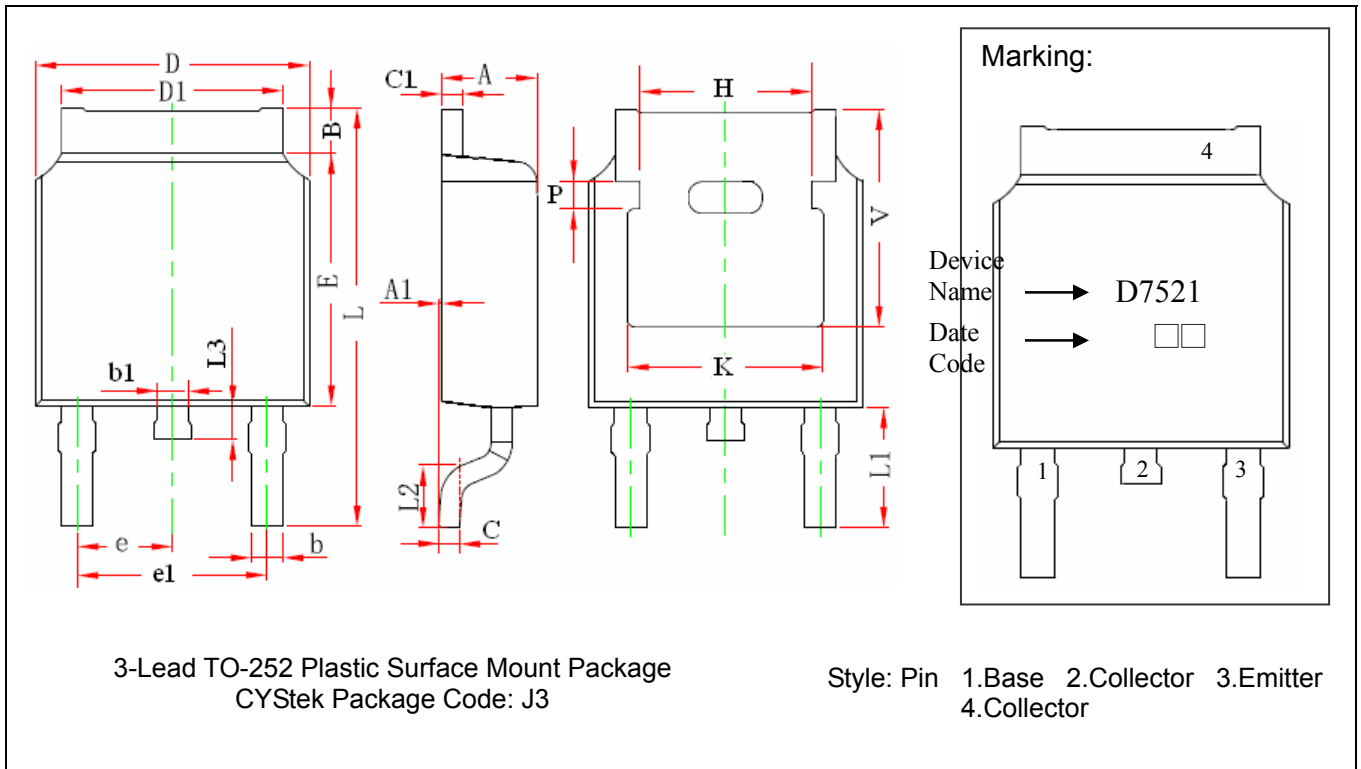
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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